



BSW SERIES

BOTTOM MOUNT SOCKET STRIPS

TSW, MTSW, HTSW,
MTLW, TSM, EW, ZW,
HW, DW, PHT

- Bottom mount socket strips accept .025" SQ terminals.
- Ideal for soldering and plugging from the same side of the board.
- For low profile connections and high temperature soldering.

For complete specifications and recommended PCB layouts see www.samtec.com?BSW

Wave only

For complete scope
of recognitions see
www.samtec.com/quality



Note: Some lengths, styles and options are non-standard, non-returnable.

BSW — **1** — **NO. PINS PER ROW**

02 thru 36

LEAD STYLE

- 04** = Standard Lead
- 24** = Low Insertion Force

PLATING OPTION

- L** = 10μ" (0,25 μm) Gold contact, Matte Tin on tail
- G** = 20μ" (0,51 μm) Gold contact, Gold Flash on tail
- T** = Matte Tin (N/A with Low Insertion Force)

ROW OPTION

- S** = Standoffs for single and double rows only.

OTHER OPTION

- D** = Double row

Dimensions:

- Pin height: (2,54) .100 TYP
- Pin pitch: (0,79) .031 TYP
- Pin diameter: (0,41) .016 TYP
- Pin spacing: (8,89) .350
- Pin length: (0,38) .015

Row Option

Row Option	Z
-S*	(4,31) .170

*Less

ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.



(No. of Pos. X (2,54) .100) + (0,51) .020

01 36

02 72

01 71

Y

X

-S
-M
-E

(2,54) .100

(2,54) .100

(10,16) .400

(2,54) .100

-D

Row Option	X	Y
-S	(2,54) .100	(5,08) .200
-M	(3,81) .150	(6,35) .250
-E	(4,31) .170	(6,86) .270

CONTACT

Body design may vary slightly from drawing shown.

-S = Single Row

-M = Single Row More Plug Space

-E = Single Row Extended Plug Space

-D = Double Row

The diagram shows a cross-section of a PCB with components on both the top and bottom surfaces. Labels include: BSW (SINGLE ROW) for a single-row ball grid array on the top; BSW (DOUBLE ROW) for a double-row ball grid array on the top; EW (SINGLE ROW) for an edge connector on the top; COMPONENT SIDE for the top surface; SOLDER SIDE for the bottom surface; TSW (SINGLE ROW) for a single-row through-hole component on the bottom; TSW (DOUBLE ROW) for a double-row through-hole component on the bottom; and BSW (SINGLE ROW) for a single-row ball grid array on the bottom.